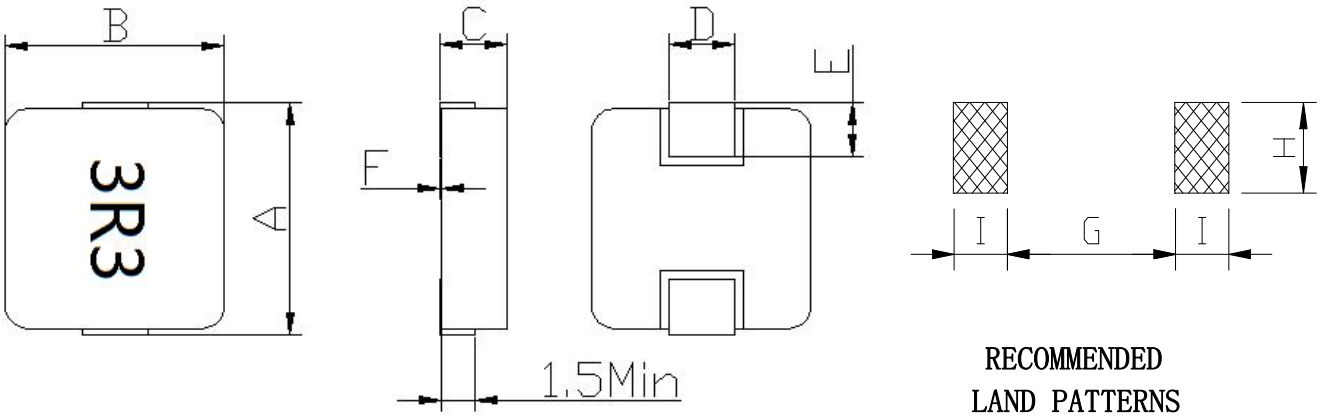
D HPI0630-003.3

Structure And Dimensions



RECOMMENDED
LAND PATTERNS

A	B	C	D	E	F TYP	G TYP	H TYP	I TYP
7.1±0.4	6.6±0.2	3.0MAX	3.0±0.3	1.5±0.5	0.15	3.6	3.5	2.4

Performance Specification

型号 Part No.	电感量 Inductance Lo(μH)±20%	Rdc (mΩ) Max	SATURATION CURRENT (Isat)	HEAT RATING CURRENT (IDC)
D HPI0630-003.3	3.3	30.0	9.0	7.0

Test equipment: Inductance\RDC---同惠 TH2827C/502BC or equivalent, Isat\Irms---同惠 TH2827C Precision LCR Meter & TH1778 BIAS.

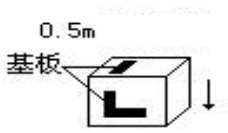
Ls Test frequency/Voltage: 100kHz/0.25V;

Isat: The DC current is that which cause a 30% inductance reduction from the initial value.

IDC: The DC current is inductor surface temperature to rise by 40℃ (Reference ambient temperature 25℃).

Reliability Data

Items	Requirements	Test Methods and Remarks
Operating Temperature Range	-40℃～+125℃	Including self-heating temperature rise.
Solderability	90% or more of electrode area shall be coated by new solder.	Dip pads in flux and dip in solder pot (96.5Sn/3.0Ag/0.5Cu) at 245 ℃±5 ℃ for (5±1) seconds.
Resistance to Soldering Heat	No visible mechanical damage. Inductance change: Within ±10%	Dip pads in flux and dip in solder pot (96.5Sn/3.0Ag/0.5Cu) at 260℃±5 ℃ for (10±1) seconds.
Low temperature stroe	No visible mechanical damage. Inductance change: Within ±10%	Stroe temperature -40±2℃ for total 1000hr.

High temperature stroe	No visible mechanical damage. Inductance change: Within ±10%	Stroe temperature 125±2℃ for total 1000hr.
Static Humidity	No visible mechanical damage. Inductance change: Within ±10%	Inductors shall be subjected to (93±3)%RH . at 40 ℃±2 ℃ for 96 h±2 h .Inductors are to be tested after having air dried for 2 hours.
Thermal shock	No visible mechanical damage. Inductance change: Within ±10%	The test sample shall be placed at (-40±3)℃ and (85±2)℃ for (30±3) min, different temperature conversion time is 2~3 minutes. The temperature cycle shall be repeated 5 cycles.
Mechanical Shock	 No evidence of terminal peel off and wire broken.	Inductors shall be Soldering on the PCB with 1.0mm thick and fixed them in a 15cm big.,1.4Kg weight cube with brass base, let it nature fallen form 0.5m height (X,Y,Z three axes)
Adhesion of terminal electrode	Strong bond between the pad and the core, without come off PC board.	Inductors shall be subjected to 260 ℃ ±5 ℃ for 20 s±5 s Soldering in the base whit 0.3mm solder. And then aplomb electrode way plus tax 10 N for 10± 1s seconds.